

Title (en)

TIN-BISMUTH SOLDER PASTE AND METHOD OF USE.

Title (de)

Zinn-Wismut-Weichlotpaste und Verfahren zu deren Verwendung.

Title (fr)

PATE DE BRASAGE D'ETAIN-BISMUTH ET PROCEDE D'UTILISATION.

Publication

EP 0655961 A1 19950607 (EN)

Application

EP 94932155 A 19940405

Priority

- US 9403730 W 19940405
- US 6964093 A 19930601

Abstract (en)

[origin: WO9427777A1] A solder paste (24 in Fig. 1) of the type utilized in forming a solder connection (32 in Fig. 2) for a microelectronic package comprises a mixture of compositionally distinct metal powders. The paste comprises a first metal powder formed of tin-bismuth solder alloy. The paste further comprises a second metal powder containing gold or silver. During reflow, the gold or silver alloys with the tin-bismuth solder to increase the melting part and enhance mechanical properties of the product connection.

IPC 1-7

B23K 35/34

IPC 8 full level

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CPC (source: EP KR US)

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